X-PLANE®

Fast and easy 3D X-ray imaging

X-plane Pro delivers high resolution 3D X-ray images of large objects such as printed circuit boards and electronics. Enabling non-destructive 3D inspection of BGAs, QFNs, Flip Chips, Micro-bumps, TSVs and other optically hidden features.

www.nordson.com/TestInspect

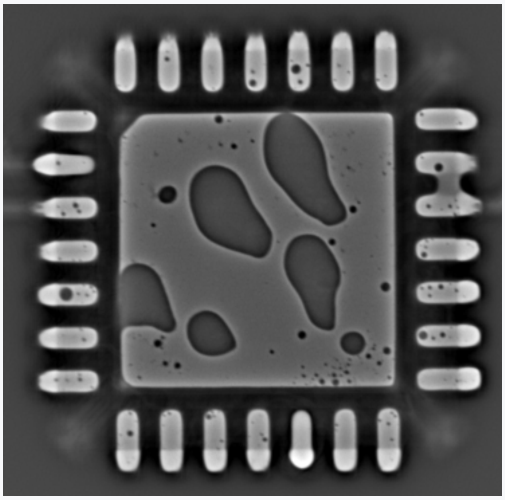
Nordson
TEST & INSPECTION

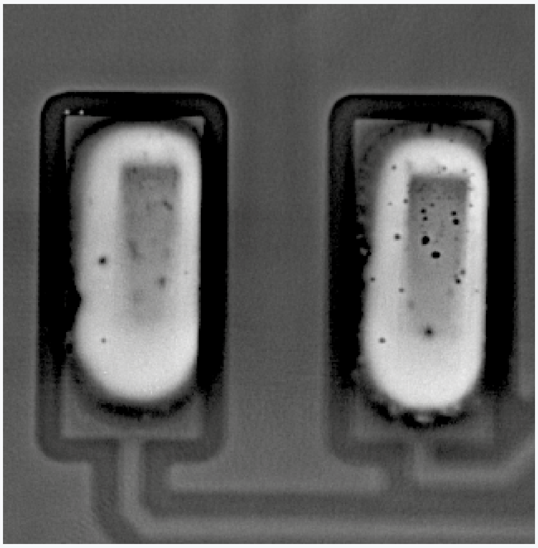
Pioneering Software

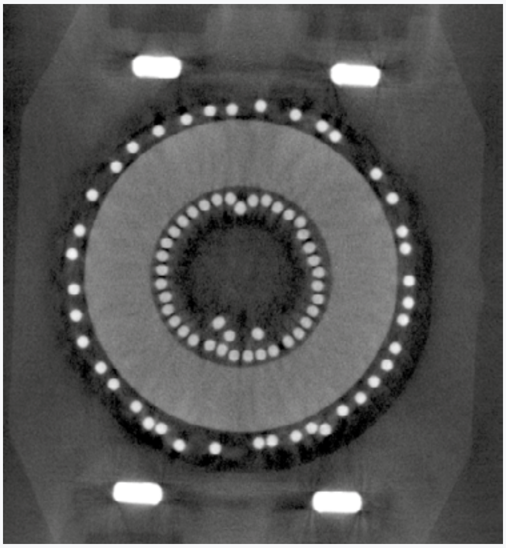
Complimentary to computed tomography (CT), X-plane Pro enables high resolution 3D imaging of large objects such as printed circuit boards without compromise on resolution.

By capturing multiple X-ray images at different angles around an object, a 3D model of the object can be created. Advanced reconstruction algorithms with intelligent artefact corrections deliver high quality 3D images.

Revealing hidden details, such as voiding or defects, without destroying the object. Ease of use and fast scan times enable high throughput.







Technical Specifications	
X-ray tube	Microfocus, 30kV – 160kV, 20W max
Max inclination angle	55° (detector centre); 65° (detector edge)
Theta angular range	0 - 360°
Field of view	1mm – 90 mm
Resolution	Up to 0.3 µm / voxel
Volume size	Up to 2000 x 2000 x 2000 voxels
Max inspection area	450mm x 400mm
Typical Scan time	30 seconds – 5 minutes
Typical reconstruction time	1 minute

For more information, speak with your Nordson representative or contact your Nordson regional office

Nordson Test & Inspection Europe, SEA, Africa
ti-sales-eu@nordson.com

Nordson Test & Inspection Americas
ti-sales-us@nordson.com

Nordson Test & Inspection China
ti-sales-cn@nordson.com

Nordson Test & Inspection Japan
ti-sales-jp@nordson.com

Nordson Test & Inspection Singapore
ti-sales-eu@nordson.com

Nordson Test & Inspection Taiwan
ti-sales-tw@nordson.com

Nordson Test & Inspection Korea
ti-sales-korea@nordson.com